



## Rectifier Diode Modules

### SKKD 95/16

#### Features\*

- Heat transfer through aluminium oxide ceramic insulated metal baseplate
- UL recognized, file no. E63532

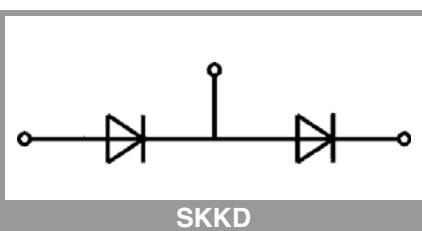
#### Typical Applications

- Non-controllable rectifiers for AC/AC converters
- Line rectifiers for transistorized AC motor controllers
- Field supply for DC motors

Absolute Maximum Ratings		Values		Unit
Symbol	Conditions			
<b>Rectifier Diode</b>				
$I_{FAV}$	sin. 180°	$T_c = 85 \text{ }^\circ\text{C}$	98	A
	$T_{j\max} = 130 \text{ }^\circ\text{C}$	$T_c = 100 \text{ }^\circ\text{C}$	74	A
$I_{FSM}$	$t_p = 10 \text{ ms}$	$T_j = 25 \text{ }^\circ\text{C}$	1850	A
		$T_j = 130 \text{ }^\circ\text{C}$	1600	A
$i^2t$	$t_p = 10 \text{ ms}$	$T_j = 25 \text{ }^\circ\text{C}$	17100	$\text{A}^2\text{s}$
		$T_j = 130 \text{ }^\circ\text{C}$	12800	$\text{A}^2\text{s}$
$V_{RSM}$	$T_j = 25 \text{ }^\circ\text{C}$		1700	V
$V_{RRM}$	$T_j = 25 \text{ }^\circ\text{C}$		1600	V
$T_j$			-40 ... 130	$^\circ\text{C}$
<b>Module</b>				
$T_{stg}$			-40 ... 125	$^\circ\text{C}$
$V_{isol}$	a.c.; 50 Hz; r.m.s.	1 min	3000	V
		1 s	3600	V

#### Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
<b>Diode</b>					
$V_F$	$T_j = 25 \text{ }^\circ\text{C}$ , $I_F = 300 \text{ A}$			1.60	V
$V_{F0}$	$T_j = 130 \text{ }^\circ\text{C}$			0.85	V
$r_F$	$T_j = 130 \text{ }^\circ\text{C}$			2.80	$\text{m}\Omega$
$I_R$	$T_j = 130 \text{ }^\circ\text{C}$ , $V_{RRM}$			2	mA
$R_{th(j-c)}$	cont.	per chip		0.23	K/W
		per module		0.115	K/W
$R_{th(j-c)}$	sin. 180°	per chip		0.30	K/W
		per module		0.15	K/W
<b>Module</b>					
$R_{th(c-s)}$	per chip ( $\lambda_{grease} = 0.81 \text{ W}/(\text{m}^*\text{K})$ )		0.09		K/W
	per module ( $\lambda_{grease} = 0.81 \text{ W}/(\text{m}^*\text{K})$ )		0.05		K/W
$M_s$	to heatsink M5		4.25	5.75	Nm
$M_t$	to terminals M5		2.55	3.45	Nm
$a$				5 * 9.81	$\text{m}/\text{s}^2$
$w$			75		g



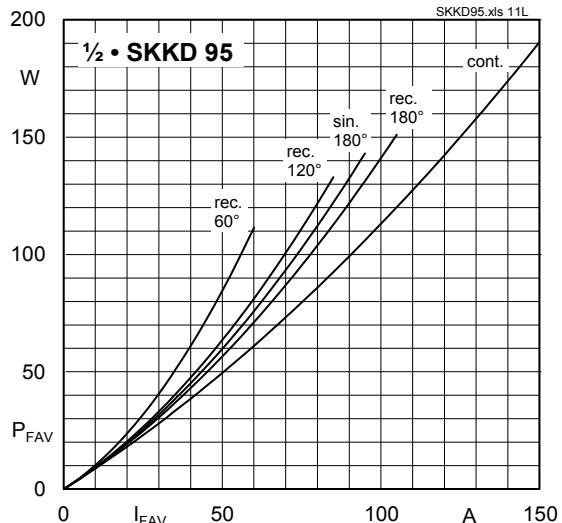


Fig. 11L: Power dissipation per diode vs. forward current

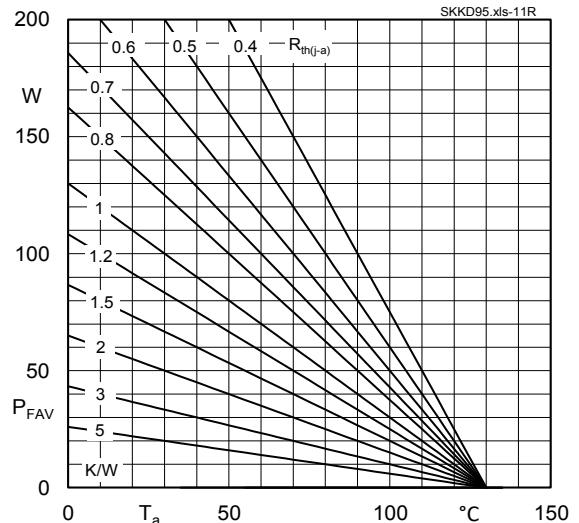


Fig. 11R: Power dissipation per diode vs. ambient temperature

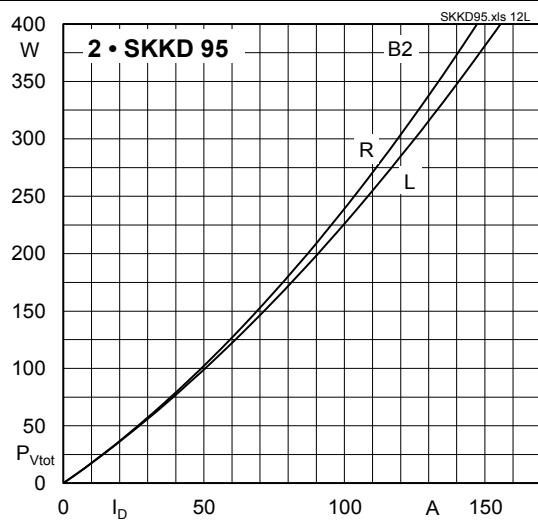


Fig. 12L: Power dissipation of two modules vs. direct current

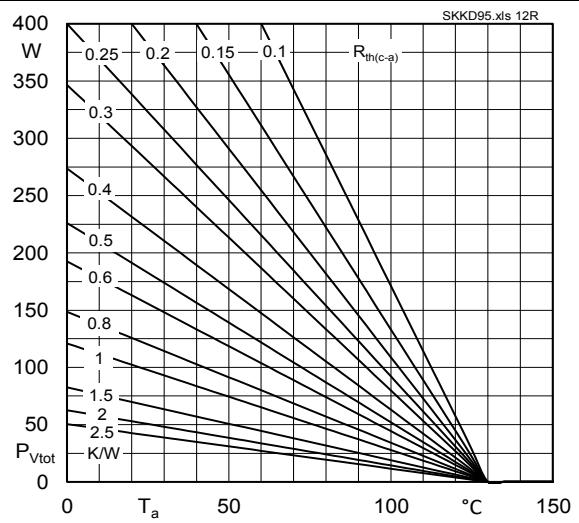


Fig. 12R: Power dissipation of two modules vs. ambient temperature

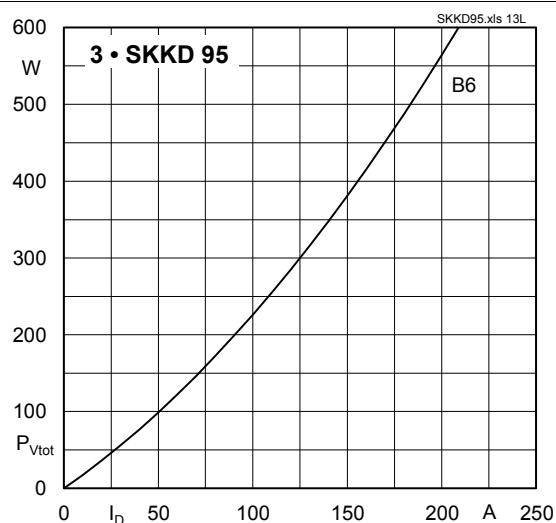


Fig. 13L: Power dissipation of three modules vs. direct current

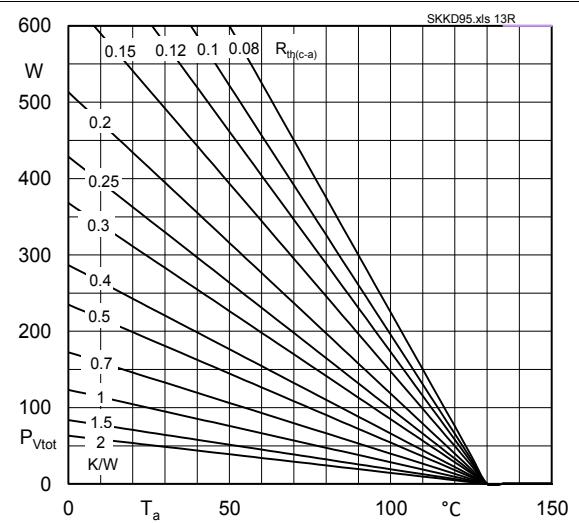


Fig. 13R: Power dissipation of three modules vs. ambient temperature

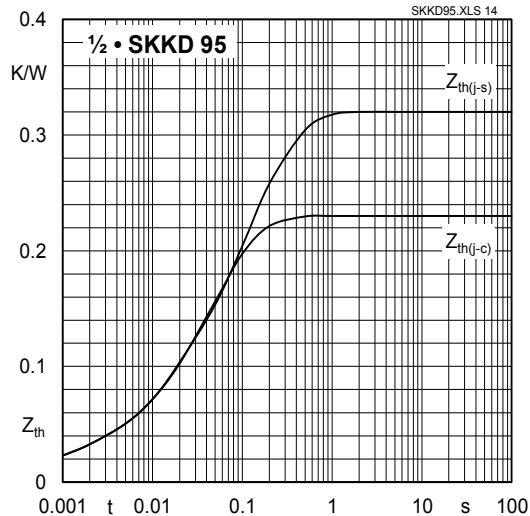


Fig. 14: Transient thermal impedance vs. time

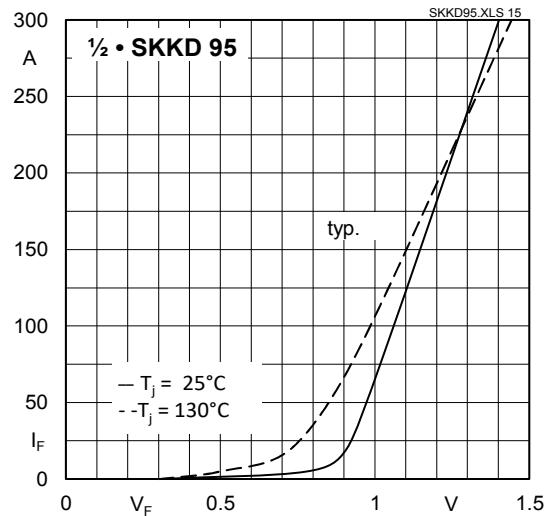


Fig. 15: Forward characteristics

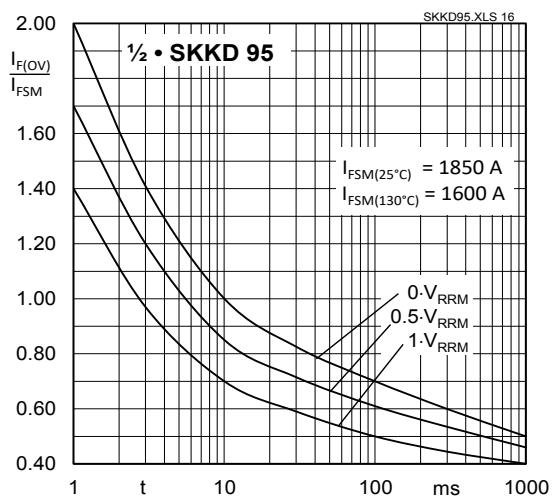


Fig. 16: Surge overload current vs. time

